



GR 00 P 4121

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By:  Date: July 17, 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Albert Birner et al.  
Appl. No. : 09/871,013  
Filed : May 31, 2001  
Title : Method for Making Electrical Contact with a Rear Side of a  
Semiconductor Substrate during its Processing  
Art Unit :

LETTER

Hon. Commissioner of Patents and Trademarks,  
Washington, D.C. 20231

Sir:

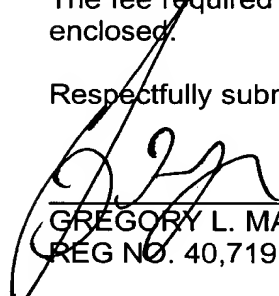
The above-mentioned new patent application was filed on May 31, 2001 without a signed oath or declaration, under the provision of 37 C.F.R. 1.53(f).

In accordance with the above-mentioned rule, enclosed herewith is the original signed declaration.

The undersigned hereby states that the application filed in the Patent and Trademark Office is the application which the inventor(s) executed by signing the declaration. MPEP 601.01(a).

The fee required for the late filing of an oath or declaration in the amount of \$130.00 is also enclosed.

Respectfully submitted,

  
GREGORY L. MAYBACK  
REG NO. 40,719

/mjb

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U.S. PATENT AND TRADEMARK OFFICE